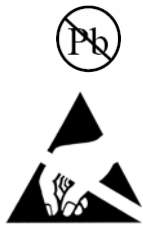


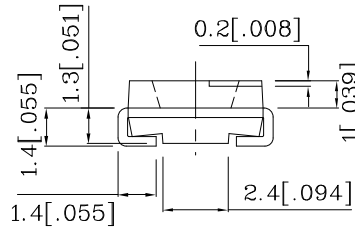
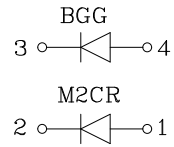
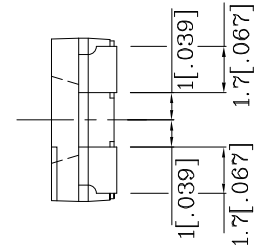
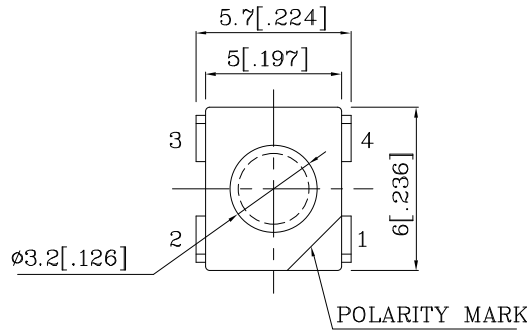
PRELIMINARY SPEC

Features

- CHIPS CAN BE CONTROLLED SEPARATELY.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- PACKAGE: 500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



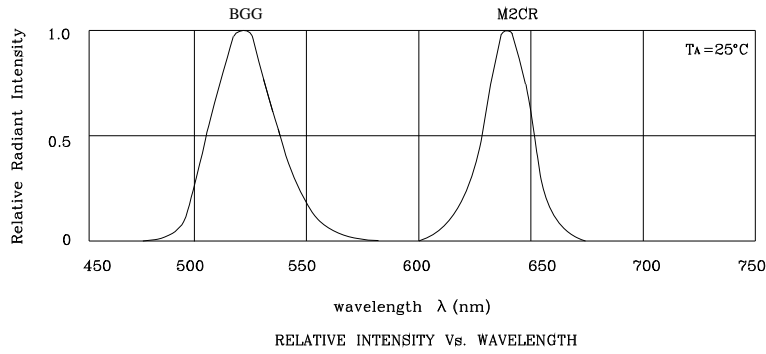
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Specifications are subject to change without notice.

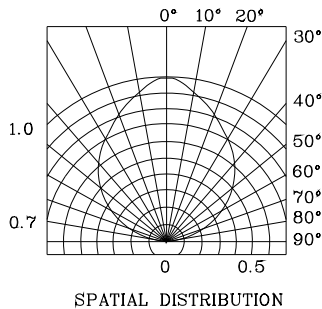
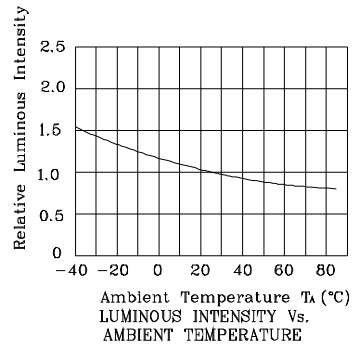
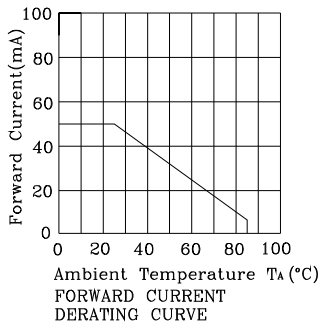
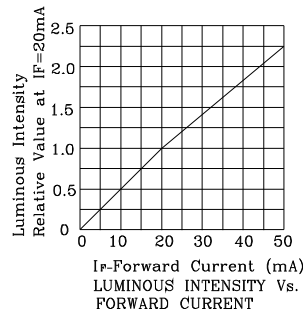
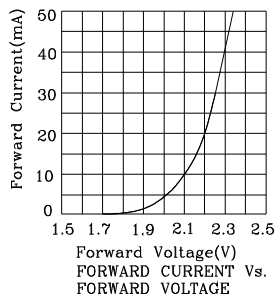
Absolute Maximum Ratings (TA=25°C)		M2CR (AlInGaP)	BGG (InGaN)	Unit
Reverse Voltage	VR	5	5	V
Forward Current	IF	50	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	150	100	mA
Power Dissipation	PT	140	120	mW
Operating Temperature		-	1000	V
Storage Temperature	TA	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~ +85		

Operating Characteristics (TA=25°C)		M2CR (AlInGaP)	BGG (InGaN)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	2.2	3.2	V
Forward Voltage (Max.) (IF=20mA)	VF	2.8	4.0	V
Reverse Current (Max.) (VR=5V)	IR	10	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λP	640	520	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λD	630	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	$\Delta\lambda$	25	35	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	27	100	pF

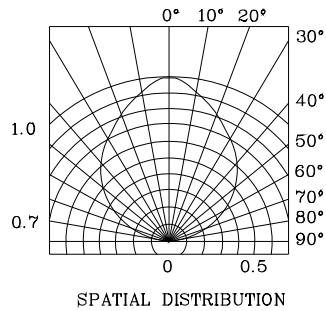
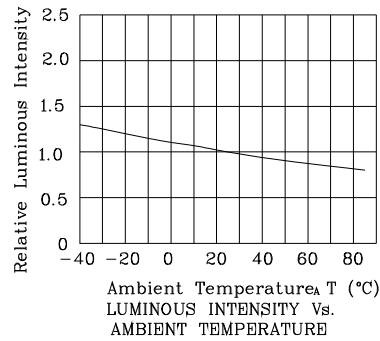
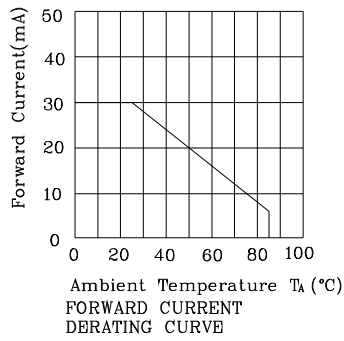
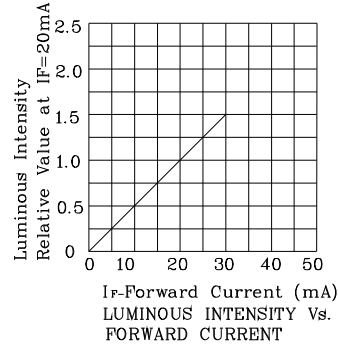
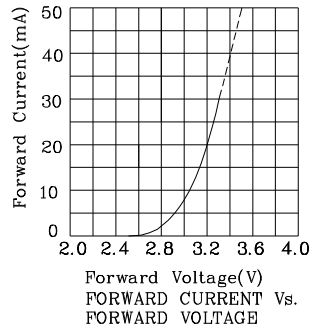
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=50mA *30mA) mcd		Wavelength nm λP	Viewing Angle 2 θ 1/2
				min.	typ.		
XZM2CRBGG82W	Red	AlInGaP	Water Clear	3300	4490	640	100°
	Green	InGaN		*380	*745	520	



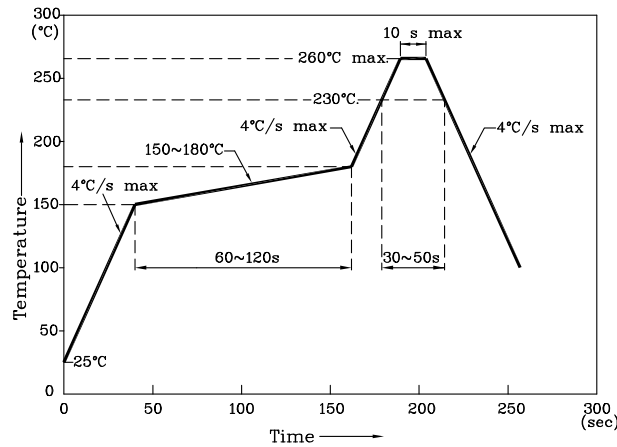
❖ M2CR



❖ BGG



Reflow Soldering Profile For Lead-free SMT Process.

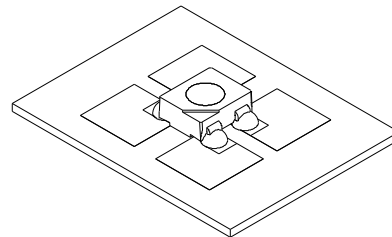
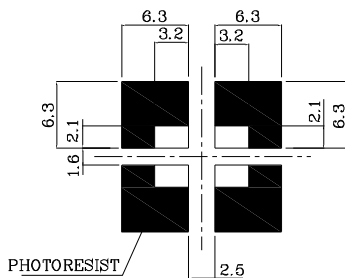


NOTES:

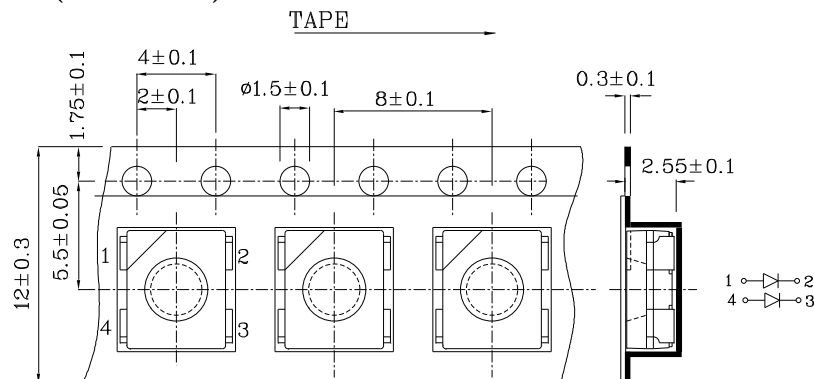
1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C–260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern
 (Units : mm; Tolerance: ±0.1)

❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

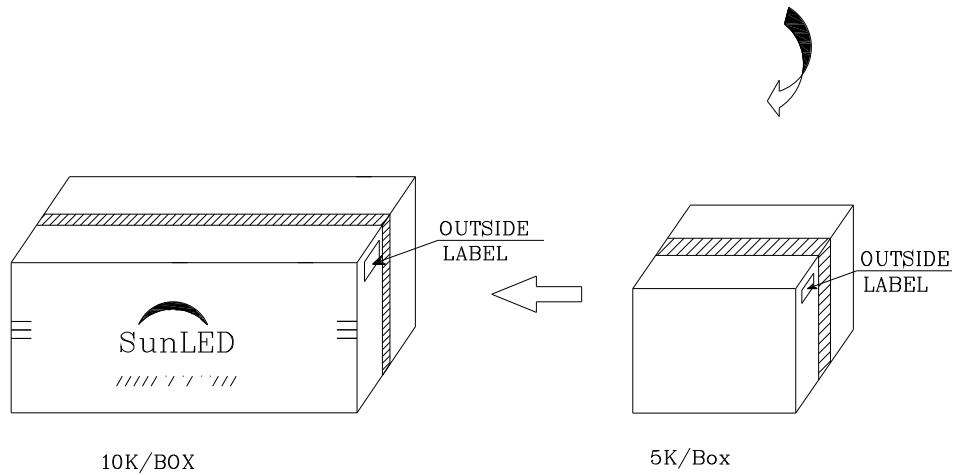
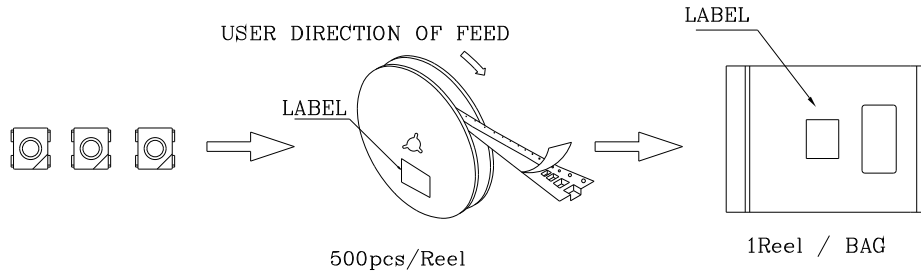

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

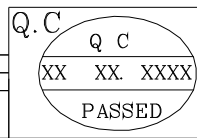

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZM2CRBGG82W

	
P/NO : XZxx82x	
QTY : 500 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	